

Product Data Sheet

# TACFlux® 008 for Electronics Assembly & Rework

## Features

- Halogen-free for Pb-free applications
- Excellent pin-probe performance
- Wide reflow profile window under both air and nitrogen
- Excellent soldering performance and process yield
- Excellent wetting to all fresh and aged surface finishes, including, but not limited to: OSP, immersion Ag, immersion Sn, and ENIG.
- Low voiding in all joints, including BGA assemblies

## Application Method

TACFlux® 008 can be dispensed in dots or lines onto the desired substrate, preform, or BGA sphere. It can also be easily screen printed or stenciled on a desired component footprint.

## Packaging

TACFlux® 008 is available in various size syringes, jars, or cartridges.

## Introduction

TACFlux® 008 is an electronics-grade no-clean creamy flux. Its many uses include: rework and repair of various electronics assemblies and components, die-attach, SMT component-attach (including BGAs & flip-chips), BGA ball-attach, preform soldering, and virtually any application where a flux is required. Cycle time is not critical as TACFlux may sit for hours with no reflow degradation.

TACFlux® 008 is compatible with a variety of no-clean solder pastes, including NC-SMQ71 Solder Paste and Indium9.52 Die-Attach Solder Paste.

## Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon and paste. Indium Corporation's Technical Support engineers provide Rapid Response to all technical inquiries.

## Material Safety Data Sheets

The MSDS for this product can be found online at <http://www.indium.com/techlibrary/msds.php>

## Properties

J-STD-004 (IPC-TM-650)	
Test	Result
Flux Type Classification	ROLO
Elemental Halogen Analysis	0%
Post Reflow Flux Residue (ICA Test)	<20%
Corrosion	Pass
SIR (ohms)	Pass (>10 <sup>9</sup> @85°C, 85% R.H.)
Acid Value	100 (typical)
Flux Viscosity: Brookfield (5rpm)	500 kcps (typical)
Tack Strength	240g (typical)
Maximum Peak Temperature	340°C (under nitrogen)
Storage Conditions	Not less than 12 months @ 0-30°C. Refrigeration is recommended, but not required.

All information is for reference only. Not to be used as incoming product specifications.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

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